

Interconnect Stress Test HC (High Capacity)



PWB Interconnect Solutions Inc. has released a new High Capacity (HC) model of its industry leading Interconnect Stress Test (IST) tool that now features 8 test heads, hot swappable coupon loading, increased resistance and voltage capacity, IPC-TM-650 Test Method 2.6.27 support, automated report generation and remote diagnostics.

The HC uses IST technology to electrically cycle test coupons to determine the reliability of a product. In addition to supporting Test Method 2.6.26, the HC now supports Test Method 2.6.27 to simulate Lead Free Solder assembly. The HC can simulate both the reflow oven and assembly rework station temperature profiles to subject the test coupon to the same temperature excursions of the actual printed circuit board assembly.

The new hot swappable coupon load / unload feature allows the user to immediately unload a failed coupon and reload a new coupon eliminating the need to wait until the last coupon in a batch of coupons has failed.

The test system incorporates custom designed power supply and high precision measurement systems which are interfaced to an user friendly application software, that automatically measures, records, analyzes data with displays and reports that simplify the understanding of the reliability of a product.

For additional information about PWB products and services, please visit <http://pwbcorp.com>.

